

Special Issue

Applications of Artificial Intelligence and Deep Learning in Computer Networks and Communications

Message from the Guest Editor

Progress in artificial intelligence and deep learning technologies is becoming increasingly integrated into computer networks and communications. The merging of these two technological domains has paved the way for a multitude of applications and services. Within this special issue, researchers from around the globe are invited to share and engage in discussions about their valuable and cherished research outcomes. We are pleased to invite you, along with the members of your research group, to contribute to the forthcoming Special Issue, entitled “Applications of Artificial Intelligence and Deep Learning in Computer Networks and Communication”.

Guest Editor

Dr. Ohyun Jo

Department of Computer Science, College of Electrical and Computer Engineering, Chungbuk National University, Cheongju 28644, Korea

Deadline for manuscript submissions

closed (20 September 2024)



Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



mdpi.com/si/198094

Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

mdpi.com/journal/

[applsci](https://doi.org/10.3390/applsci)





Applied Sciences

an Open Access Journal
by MDPI

Impact Factor 2.5
CiteScore 5.5



[mdpi.com/journal/
applsci](https://mdpi.com/journal/applsci)



About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

Author Benefits

Open Access:

free for readers, with article processing charges (APC) paid by authors or their institutions.

High Visibility:

indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, CAPlus / SciFinder, and other databases.

Journal Rank:

JCR - Q2 (Engineering, Multidisciplinary) / CiteScore - Q1 (General Engineering)